

Interview Summary	Application No. 10/604,013	Applicant(s) MILILLO ET AL.	
	Examiner Patrick H. Mackey	Art Unit 3651	

All participants (applicant, applicant's representative, PTO personnel):

- (1) Patrick H. Mackey. (3) _____
 (2) Jerry Thielman. (4) _____

Date of Interview: 05 November 2004.

Type: a) ☐ Telephonic b) ☐ Video Conference
 c) ☒ Personal [copy given to: 1) ☐ applicant 2) ☒ applicant's representative]

Exhibit shown or demonstration conducted: d) ☐ Yes e) ☐ No.
 If Yes, brief description: _____

Claim(s) discussed: All independent.

Identification of prior art discussed: All cited references.

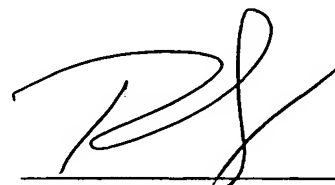
Agreement with respect to the claims f) ☒ was reached. g) ☐ was not reached. h) ☐ N/A.

Substance of Interview including description of the general nature of what was agreed to if an agreement was reached, or any other comments: Attorney proposed claim language which the examiner agreed would overcome the art of record.

(A fuller description, if necessary, and a copy of the amendments which the examiner agreed would render the claims allowable, if available, must be attached. Also, where no copy of the amendments that would render the claims allowable is available, a summary thereof must be attached.)

THE FORMAL WRITTEN REPLY TO THE LAST OFFICE ACTION MUST INCLUDE THE SUBSTANCE OF THE INTERVIEW. (See MPEP Section 713.04). If a reply to the last Office action has already been filed, APPLICANT IS GIVEN ONE MONTH FROM THIS INTERVIEW DATE, OR THE MAILING DATE OF THIS INTERVIEW SUMMARY FORM, WHICHEVER IS LATER, TO FILE A STATEMENT OF THE SUBSTANCE OF THE INTERVIEW. See Summary of Record of Interview requirements on reverse side or on attached sheet.

Examiner Note: You must sign this form unless it is an Attachment to a signed Office action.



Examiner's signature, if required

Summary of Record of Interview Requirements

Manual of Patent Examining Procedure (MPEP), Section 713.04, Substance of Interview Must be Made of Record

A complete written statement as to the substance of any face-to-face, video conference, or telephone interview with regard to an application must be made of record in the application whether or not an agreement with the examiner was reached at the interview.

Title 37 Code of Federal Regulations (CFR) § 1.133 Interviews

Paragraph (b)

In every instance where reconsideration is requested in view of an interview with an examiner, a complete written statement of the reasons presented at the interview as warranting favorable action must be filed by the applicant. An interview does not remove the necessity for reply to Office action as specified in §§ 1.111, 1.135. (35 U.S.C. 132)

37 CFR §1.2 Business to be transacted in writing.

All business with the Patent or Trademark Office should be transacted in writing. The personal attendance of applicants or their attorneys or agents at the Patent and Trademark Office is unnecessary. The action of the Patent and Trademark Office will be based exclusively on the written record in the Office. No attention will be paid to any alleged oral promise, stipulation, or understanding in relation to which there is disagreement or doubt.

The action of the Patent and Trademark Office cannot be based exclusively on the written record in the Office if that record is itself incomplete through the failure to record the substance of interviews.

It is the responsibility of the applicant or the attorney or agent to make the substance of an interview of record in the application file, unless the examiner indicates he or she will do so. It is the examiner's responsibility to see that such a record is made and to correct material inaccuracies which bear directly on the question of patentability.

Examiners must complete an Interview Summary Form for each interview held where a matter of substance has been discussed during the interview by checking the appropriate boxes and filling in the blanks. Discussions regarding only procedural matters, directed solely to restriction requirements for which interview recordation is otherwise provided for in Section 812.01 of the Manual of Patent Examining Procedure, or pointing out typographical errors or unreadable script in Office actions or the like, are excluded from the interview recordation procedures below. Where the substance of an interview is completely recorded in an Examiners Amendment, no separate Interview Summary Record is required.

The Interview Summary Form shall be given an appropriate Paper No., placed in the right hand portion of the file, and listed on the "Contents" section of the file wrapper. In a personal interview, a duplicate of the Form is given to the applicant (or attorney or agent) at the conclusion of the interview. In the case of a telephone or video-conference interview, the copy is mailed to the applicant's correspondence address either with or prior to the next official communication. If additional correspondence from the examiner is not likely before an allowance or if other circumstances dictate, the Form should be mailed promptly after the interview rather than with the next official communication.

The Form provides for recordation of the following information:

- Application Number (Series Code and Serial Number)
- Name of applicant
- Name of examiner
- Date of interview
- Type of interview (telephonic, video-conference, or personal)
- Name of participant(s) (applicant, attorney or agent, examiner, other PTO personnel, etc.)
- An indication whether or not an exhibit was shown or a demonstration conducted
- An identification of the specific prior art discussed
- An indication whether an agreement was reached and if so, a description of the general nature of the agreement (may be by attachment of a copy of amendments or claims agreed as being allowable). Note: Agreement as to allowability is tentative and does not restrict further action by the examiner to the contrary.
- The signature of the examiner who conducted the interview (if Form is not an attachment to a signed Office action)

It is desirable that the examiner orally remind the applicant of his or her obligation to record the substance of the interview of each case. It should be noted, however, that the Interview Summary Form will not normally be considered a complete and proper recordation of the interview unless it includes, or is supplemented by the applicant or the examiner to include, all of the applicable items required below concerning the substance of the interview.

A complete and proper recordation of the substance of any interview should include at least the following applicable items:

- 1) A brief description of the nature of any exhibit shown or any demonstration conducted,
- 2) an identification of the claims discussed,
- 3) an identification of the specific prior art discussed,
- 4) an identification of the principal proposed amendments of a substantive nature discussed, unless these are already described on the Interview Summary Form completed by the Examiner,
- 5) a brief identification of the general thrust of the principal arguments presented to the examiner,
(The identification of arguments need not be lengthy or elaborate. A verbatim or highly detailed description of the arguments is not required. The identification of the arguments is sufficient if the general nature or thrust of the principal arguments made to the examiner can be understood in the context of the application file. Of course, the applicant may desire to emphasize and fully describe those arguments which he or she feels were or might be persuasive to the examiner.)
- 6) a general indication of any other pertinent matters discussed, and
- 7) if appropriate, the general results or outcome of the interview unless already described in the Interview Summary Form completed by the examiner.

Examiners are expected to carefully review the applicant's record of the substance of an interview. If the record is not complete and accurate, the examiner will give the applicant an extendable one month time period to correct the record.

Examiner to Check for Accuracy

If the claims are allowable for other reasons of record, the examiner should send a letter setting forth the examiner's version of the statement attributed to him or her. If the record is complete and accurate, the examiner should place the indication, "Interview Record OK" on the paper recording the substance of the interview along with the date and the examiner's initials.

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A substrate-compiling device usable to compile a number of substrates, comprising:

an input path usable to receive a substrate to be compiled, the input path defining a process direction for the substrate;

a compiler platform usable to receive the substrate to be compiled from the input path and to compile the received substrate into a set of at least one substrate;

at least one gate usable to direct the received substrate from the input path to the compiler platform; and

a stack platform positioned below the compiler platform usable to ~~received~~ receive the compiled set of at least one substrate, wherein the compiler platform comprises:

a first shelf member, and

a second shelf member,

PROPOSED

wherein the first and second shelf members define a surface on which the received substrate is compiled onto, the first and second shelf members ~~movable away~~ from each other along a ~~second~~ shelf-moving direction having a perpendicular translation component to the process direction of the substrate to allow the compiled set of at least one substrate to drop to the stack platform.

2. (Original) The substrate-compiling device of claim 1, further comprising a tamper device usable to tamp against a trailing edge of the received substrate when the received substrate is compiled onto the surface to drive a leading edge of the received substrate against a registration surface of the compiling device.

3. (Original) The substrate-compiling device of claim 1, wherein the first and second shelf members each include a tamping surface usable to tamp against a side edge of the received substrate when the received substrate is compiled onto the surface to laterally align the compiled set of at least one substrate.

4. (Currently Amended) The substrate-compiling device of claim 3, wherein the first and second shelf members are moved laterally back and forth along the ~~second shelf-~~moving direction to tamp against the side edges of the received substrate.

5. (Currently Amended) The substrate-compiling device of claim 4, wherein the first and second ~~substrates~~ shelf members are moved away from each other a ~~first~~ distance to allow the compiled set of at least one substrate to drop onto the stack platform and are moved away from each other less than the ~~first~~ distance when moving laterally back and forth along the ~~second shelf-moving~~ direction to tamp against the side edges of the received substrate.

6. (Original) The substrate-compiling device of claim 1, further comprising a manipulation device usable to manipulate the compiled set of at least one substrate before the compiled set of at least one substrate is dropped to the stack platform.

7. (Original) The substrate-compiling device of claim 6, wherein the manipulation device includes a registration surface, the substrate-compelling device further comprising a tamper device usable to tamp against a trailing edge of the received substrate when the received substrate is compiled onto the surface to drive a leading edge of the received substrate against the registration surface of the manipulation device.

8. (Original) The substrate-compiling device of claim 7, wherein the manipulation device is further usable to manipulate the compiled set of at least one substrate registered against the registration surface without having to move the compiled set of at least one substrate along the process direction before manipulating the substrate.

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9. (Currently Amended) The substrate-compiling device of claim 8, wherein the manipulation device further comprises an ejection device usable to move the compiled set of at least one substrate away from the registration surface and out of the manipulation device, such that the first and second shelf members can be moved away from each other along the ~~second~~ shelf-moving direction to allow the compiled set of at least one substrate to drop to the stack platform.

10. (Original) The substrate-compiling device of claim 6, wherein the manipulation device is at least one of a stapler, a hole punch, and a substrate perforator.

11. (Currently Amended) A method for compiling a substrate into a set of at least one substrate, comprising:

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receiving the substrate at an input of a substrate-compiling device, the substrate traveling along a process direction;

directing the received substrate onto a compiler platform comprising a first shelf member and a second shelf member that define a compiling surface;

compiling the received substrate and zero, one or more other substrates into a compiled set of at least one substrate; and

moving the first and second shelf members away from each other along a ~~second~~ shelf-moving direction having a translation component that is perpendicular to the process direction to allow the compiled set of at least one substrate to drop onto a stack platform that is positioned below the compiler platform.

12. (Original) The method of claim 11, further comprising tamping against a trailing edge of the received substrate when the received substrate is compiled onto the compiling surface to drive a leading edge of the received substrate against a registration surface of the compiling device.

13. (Original) The method of claim 11, wherein the first and second shelf members each includes a tamping surface, the method further comprising tamping the tamping surfaces of the first and second shelf members against the side edges of the received substrate when the received substrate is compiled onto the compiling surface to align the received substrate.

14. (Currently Amended) The method of claim 13, wherein the tamping surfaces of the first and second shelf members against the side edges of the received substrate when the received substrate is compiled onto the compiling surface comprises moving the first and second shelf members laterally back and forth along the ~~second~~ shelf-moving direction to tamp the tamping surfaces against the side edges of the received substrate.

15. (Currently Amended) The method of claim 14, wherein:
moving the first and second shelf members away from each other along a ~~second~~ shelf-moving direction that is perpendicular to the process direction to allow the compiled set of at least one substrate to drop to a stack platform comprises moving the first and second shelf members away from each other by a ~~first~~ distance; and

moving the first and second substrates back and forth along the ~~second~~ shelf-moving direction to tamp against the received substrate comprises moving the first and second shelf members away from each other less than the ~~first~~ distance when moving laterally back and forth along the ~~second~~ shelf-moving direction.

16. (Original) The method of claim 11, further comprising manipulating the compiled set of at least one substrate before dropping the compiled set of at least one substrate to the stack platform.

17. (Original) The method of claim 16, wherein the substrate-compiling device includes a manipulation device having a registration surface, the method further comprising:

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tamping against a trailing edge of the received substrate when the received substrate is compiled onto the compiling surface to drive a leading edge of the received substrate against the registration surface of the manipulation device.

18. (Currently Amended) The method of claim 17, further comprising manipulating the compiled set of at least one substrate using the ~~manipulating~~ manipulation device without having to first move the compiled set of at least one substrate along the process direction before manipulating the substrate.

19. (Currently Amended) The method of claim 18, further comprising ejecting the compiled set of at least one substrate away from the registration surface, out of the manipulation device and onto the compiling surface, such that the first and second shelf members can be moved away from each other along the ~~second~~ shelf-moving direction to allow the compiled set of at least one substrate to drop to the stack platform.

20. (Original) The method of claim 16, wherein manipulating the compiled set of at least one substrate comprises at least one of at least stapling the compiled set of at least one substrate at least once, punching at least one hole into the compiled set of at least one substrate, and creating at least one perforation in at least one substrate of the compiled set of at least one substrate.

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